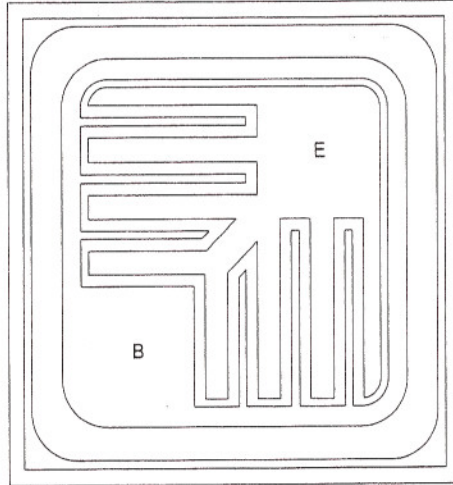




Sierra Components, Inc.

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GEOMETRY



BACKSIDE COLLECTOR

R1

GROSS DIE PER 4 INCH WAFER

12,550

PRINCIPAL DEVICE TYPES

2N5682

2N3501

Process	EPITAXIAL PLANAR
Die Size	30 x 30 MILS
Die Thickness	7.0 MILS
Base Bonding Pad Area	8.0 x 8.0 MILS
Emitter Bonding Pad Area	7.6 x 7.6 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 10,000Å

Top Material: Al
Backside Material: Au
Bond Pad Size: .0076-.008
Backside Potential:
Mask Ref:

APPROVED BY: JK

DIE SIZE : .030 x .030

DATE: 6/27/07

MFG: CENTRAL SEMI

THICKNESS: .007

P/N:2N5682